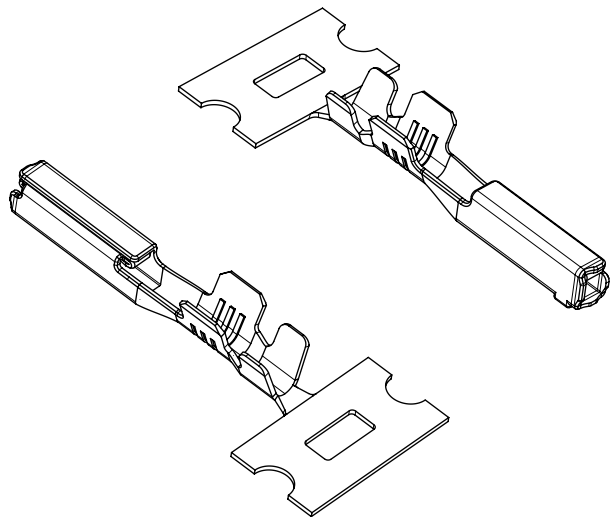
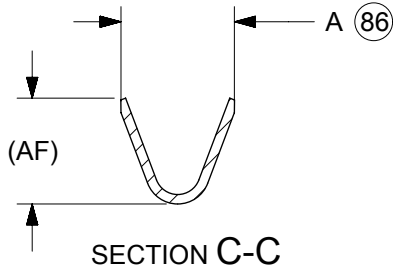
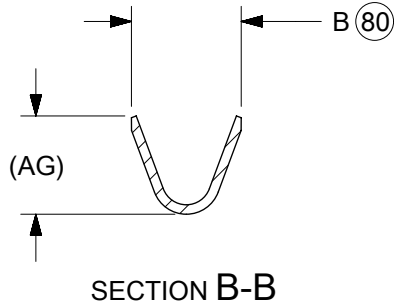
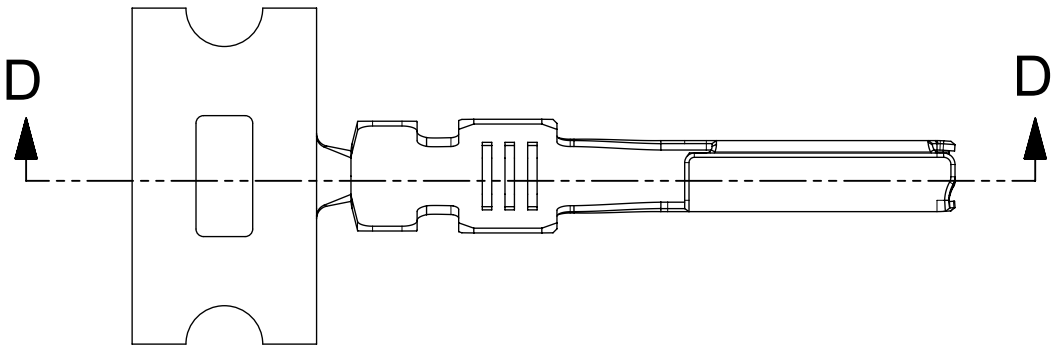
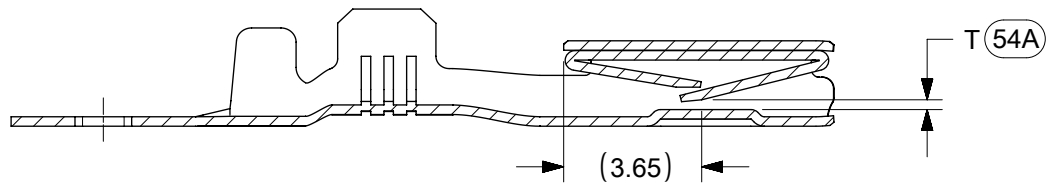
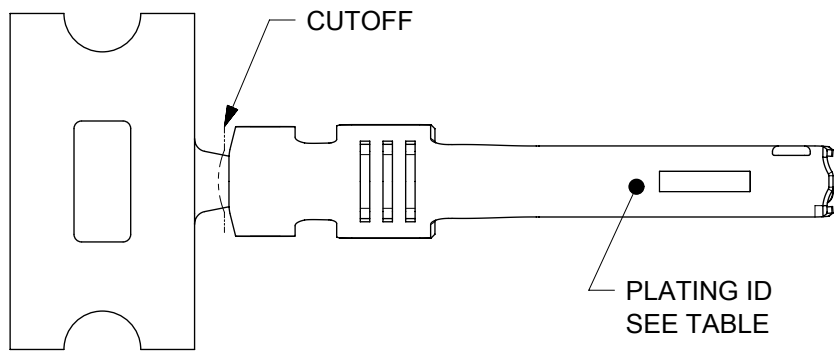
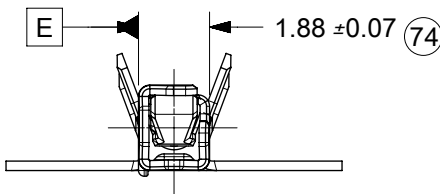
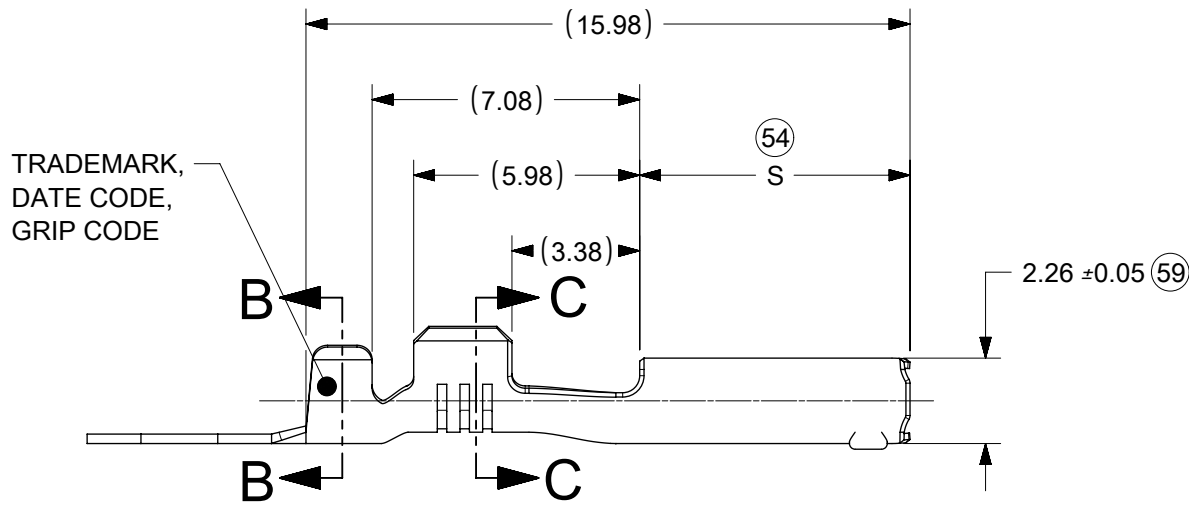
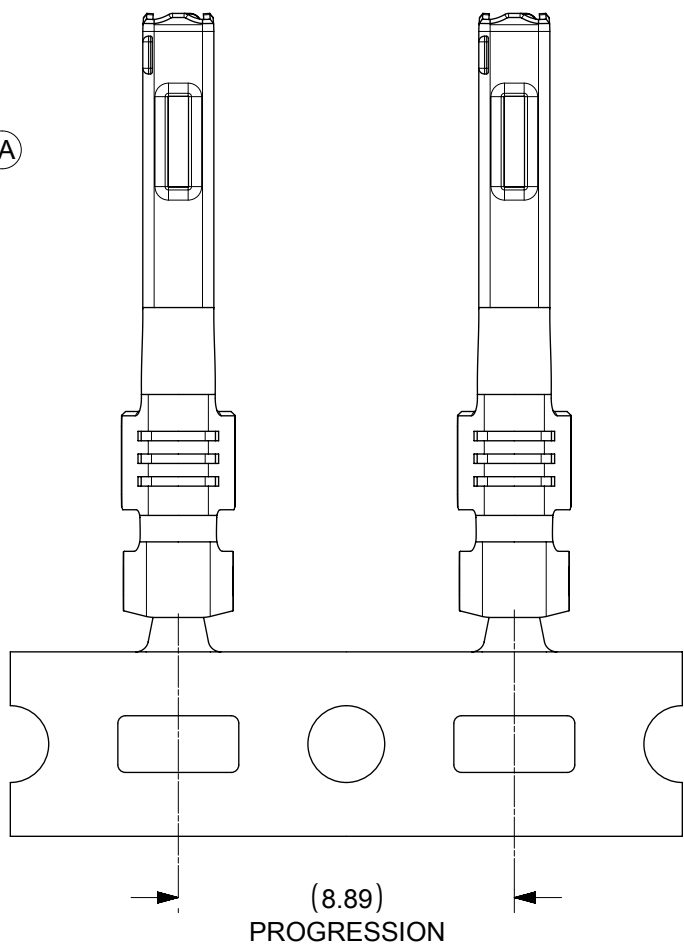




ISO VIEWS
SCALE 3:1

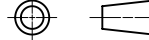
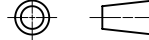


SECTION D-D



- NOTES: (UNLESS OTHERWISE SPECIFIED)
- MATERIALS: SEE TABLE
 - PACKAGING SPECIFICATION: PK-31300-516 AND PK-30907-759
 - CRIMPING PER APPLICATION SPECIFICATION AS-33468-001
 - CRIMPED LEAD MEETS THE FOLLOWING:
 - SAE/USCAR-21, MAY 2002
 - SAE/USCAR-2, REV. 3, APRIL 2001
 - SAE/USCAR-12, REV. 2
 - GMW #3191 AUGUST 22, 2000 (DRAFT) TEMPERATURE CLASS 3, APPLIES ONLY TO Au PARTS
 - GMW #3191 JANUARY, 2005 TEMPERATURE CLASS 3, APPLIES ONLY TO Ag PARTS
 - PLATING NOTES:
 - TIN PLATING (ENTIRE TERMINAL)
 - ELECTRO REFLOW 1.90 - 3.30 MICROMETERS TIN OVER 0.25 - 0.76 MICROMETERS NICKEL
 - GOLD PLATING
 - UNDERPLATE OVERALL 1.25-2.25 MICROMETERS DUCTILE SULPHAMATE NICKEL
 - ELECTRODEPOSITED GOLD 0.76 - 1.5 MICROMETERS IN CONTACT AREAS
 - ELECTRODEPOSITED TIN MATTE FINISH 2.5 - 4.0 MICROMETERS IN CRIMP AREA
 - SILVER PLATING
 - UNDERPLATE OVERALL 1.25-2.25 MICROMETERS DUCTILE SULPHAMATE NICKEL
 - ELECTRODEPOSITED PURE SILVER 99.5% PURITY SEMI-BRIGHT FINISH WITH NO BRIGHTENERS OR CHROMATES 1.9 - 3.3 MICROMETERS IN CONTACT AREAS
 - ANTI-TARNISH TREATMENT FOR SILVER PLATED AREA: SYNTHETIC HYDROCARBON CONTACT SURFACE FINISH OR EQUIVALENT
 - ELECTRODEPOSITED TIN MATTE FINISH 2.5 - 4.0 MICROMETERS IN CRIMP AREA

WIRE SIZE	GRIP CODE	PART NUMBER	REEL PAYOFF DIRECTION	DIM A	DIM B	DIM S	DIM T	DIM AF	DIM AG	BASE MATERIAL	PLATING ID
22 AWG	A	33468-0002	D	2.3	2.3	7.15	0.26	(2.1)	(2.1)	COPPER ALLOY	Sn Lead Free
		33468-0001	B			±0.10	±0.07				
		33467-0004	D	2.3	2.3	6.97-	0.26	(2.1)	(2.1)	COPPER ALLOY	Au Lead Free
		33467-0003	B			7.27	±0.07				
		34736-1001	D	2.3	2.3	6.97-	0.26	(2.1)	(2.1)	COPPER ALLOY	Ag Lead Free
		34736-2001	B			7.27	±0.07				
18/20 AWG	B	33468-0004	D	3.0	2.9	7.15	0.26	(2.8)	(2.6)	COPPER ALLOY	Sn Lead Free
		33468-0003	B			±0.10	±0.07				
		33467-0006	D	3.0	2.9	6.97-	0.26	(2.8)	(2.6)	COPPER ALLOY	Au Lead Free
		33467-0005	B			7.27	±0.07				
		34736-1002	D	3.0	2.9	6.97-	0.26	(2.8)	(2.6)	COPPER ALLOY	Ag Lead Free
		34736-2002	B			7.27	±0.07				

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION														
DIMENSION UNITS		SCALE		CURRENT REV DESC:				molex						
mm		5:1												
GENERAL TOLERANCES (UNLESS SPECIFIED)				EC NO: 601885 DRWN: NVENKATESHSH 2018/05/31 CHK'D: JPRUNEAU 2018/08/09 APPR: TOMSMITH 2018/08/13				MX64 SAE RECEPTACLE TERMINAL						
ANGULAR TOL ± 3														
4 PLACES		±												
3 PLACES		±												
2 PLACES		± 0.10												
1 PLACE		± 0.3		INITIAL REVISION:				PRODUCT CUSTOMER DRAWING						
0 PLACES		±												
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				THIRD ANGLE PROJECTION 		DRAWING C-SIZE		SERIES 33468		DOCUMENT NUMBER		DOC TYPE	DOC PART	REVISION
										SD-33468-001		PSD	001	G3
						C-SIZE		33468		MATERIAL NUMBER		CUSTOMER		SHEET NUMBER
										SEE TABLE		GENERAL MARKET		1 OF 1

molex

MX64 SAE
RECEPTACLE TERMINAL

PRODUCT CUSTOMER DRAWING

SD-33468-001

G3

DOCUMENT STATUS	P1	RELEASE DATE	2018/08/13	12:08:30
-----------------	----	--------------	------------	----------